ABSTRACT OF THE DISCLOSURE

To realize low-profile electronic apparatus (a memory module and a memory card) of a large storage size by mounting tape carrier packages (TCPs) with a memory chip encapsulated onto a wiring board in high density. To be more specific, a TCP is composed of an insulating tape, leads formed on one side thereof, a potting resin with a semiconductor chip encapsulated, and a pair of support leads arranged on two opposite short sides. The pair of support leads function to hold the TCP at a constant tilt angle relative to the mounting surface of the wiring board. By varying the length vertical to the mounting surface, the TCP can be mounted to a desired tilt angle.

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